

ABSTRACT OF THE DISCLOSURE

A novel adhesive cures quickly at a lower temperature and ensures reliable connection of objects the adhesive connects with each other. The adhesive includes a metal chelate, a silane coupling agent and a thermosetting resin. The silane coupling agent in the adhesive is hydrolyzed at its alkoxy groups to form silanol groups, which in turn react with the metal chelate to produce cations in the adhesive. The resulting cations cause the epoxy resin as a thermosetting resin, to undergo cationic polymerization. The adhesive of the present invention cures at a lower temperature by taking advantage of the cationic polymerization.

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